

G-777

Product Description

Shin-Etsu's G-777 thermal interface grease is a high reliability product that offers high resistance to pump-out, creep, and oil separation. G-777 also offers excellent thermal conductivity and electrical properties. G-777 is an all purpose grease that offers a balance of working properties including heat resistance, thermal conductivity, and pump-out resistance.

Product Features

- Excellent thermal conductivity
- Excellent electrical properties
- All-purpose high reliability product

Typical Applications

- Semiconductor elements and heat sinks requiring high reliability

Typical Properties

Type	Thermal Grease
One/Two Component	One
Low Molecular Weight Siloxane Stripped?	Y
Color	White
Density @ 23C (g/cm ³)	3.20
Viscosity (Pa·s)	140
Penetration (1/10mm)	190
Dielectric Strength (kV/mm)	12.8
Thermal Conductivity (W/m·K)	3.30
% Volatile Content	0.10
Usable Temp. Range (C)	-40 to +200

Note: Values are not for specification purposes.

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